

The 2nd Taiwan-Japan Joint Symposium in Taiwan

Chairman: Weileun Fang (National Tsing Hua Univ.)
Co-Chairman: Sheng-Shian Li (National Tsing Hua Univ.)
Co-chairman: K. Arimoto (Okayama Univ.)
Workshop chair: M. Goto (NHK)
Research meeting chair: S. Hata (Nagoya Univ.)

The study group of the Integrated MEMS of the Japan Society of Applied Physics (JSAP) will hold 2nd Taiwan-Japan Joint Symposium in Taiwan on 31st May – 1st June 2018 during Nano Engineering and Microsystem Technology Conference, which is domestic conference in Taiwan on 1st June – 2nd June 2018 (<http://www.nma.tw/>). The purpose of this joint symposium is carried out as the interchange between Taiwan and Japan, which is following the 1st joint symposium held at Hirado, Japan in 2016.

In the tenth anniversary of the study group of the Integrated MEMS, we plan the 2nd Taiwan-Japan Joint Symposium as the joint of the workshop and meeting at the study group. Based on the contents of the workshop which is comprised of the tour and poster session, the program includes the technical tour in Hsinchu area on the first day and joint symposium on the second day. The joint symposium consists of plenary talk, four invited talks, regular poster session, and banquet.

In the plenary talk and the invited talks, you could have the valuable opportunity to hear the state-of-the art talks with the IoT device, the trend of LSI, material for CMOS-MEMS, the integrated MEMS approach, and CMOS-MEMS technology.

Please submit your paper and join the symposium. We are looking forward to seeing you in Taiwan.

● Schedule & Program

[Technical tour] Thursday, May 31st 2018, Hsinchu area

- ◆ 12:00-13:10 Lunch reception dinner (<https://www.facebook.com/Socratescoffe/>).
- ◆ 13:30-17:00 The technical tour schedule in Hsinchu area:
 - 13:30~14:30 CIC (<https://www.cic.org.tw/english/index.jsp>)
 - 14:35~15:35 NDL(<http://www.ndl.org.tw/>)
 - 16:00~17:00 ITRC (<http://www.itrc.narl.org.tw/>)

[Joint symposium] Friday, June 1st 2018, Taipei area

- ◆ 11:20-12:00 Plenary talk
Prof. Hiroshi Toshiyoshi (Univ. of Tokyo),
“MEMS Vibrational Energy Harvester for IoT Wireless Sensor Applications”
- ◆ 12:00-13:30 Break
- ◆ 13:30-14:00 Poster session: Short presentation
Each poster presenter will give 2 minutes short presentation for the poster.
- ◆ 14:30-15:50 Japan-Taiwan joint session
 - 14:30-14:50 Dr. Ralph Tsung-Hsien Lin (TDK InvenSense Inc.),
“Miniaturized Pressure Sensor Technology through Integrated MEMS Approach”
 - 14:50-15:10 Prof. Toshiro Hiramoto (Univ. of Tokyo) ,
“Advanced CMOS Devices for VLSI: Present Status and Roadmap”
 - 15:10-15:30 Prof. Masato Sone (Tokyo Inst. of Tech.),
“Characteristics of Electroplated Gold Material with Multilayer Metal Technology for CMOS-MEMS Accelerometer”
 - 15:30-15:50 Prof. Tim Chih-Ting Lin (National Taiwan University),
“CMOS-NEMS Integration for Bio and Chemical Sensing”
- ◆ 15:50-16:00 Break
- ◆ 16:00-17:30 Poster session
- ◆ 18:30-20:00 Banquet Fullon Hotel (free of charge)
- Paper submission: Authors should submit one-page summary for poster session. Submissions will be accepted until May 17th 2018. Paper should include your original research work. Technical introduction from the company is also acceptable.
- Participation application
 - The technical tour: please apply to a secretariat (following e-mail address) by April 13rd 2018.
 - Joint symposium and banquet: please apply to a secretariat (following e-mail address) by May 24th 2018.
- Registration fee: Workshop member: no charge, Non-member: 5000 Japanese yen
(You can be a member if you apply.)
- Excellent poster award: Excellent poster award will be given to the selected paper.
- Contact information, Secretariat e-mail: integmems@lsi.pi.titech.ac.jp
When you apply the symposium, please include the following information in e-mail.
Name / Affiliation / E-mail address / Phone number / Mailing address /
Member information (member/non-member/student) /
Attendance to technical tour (Yes/No) / Attendance to banquet (Yes/No)